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7. The method of claim 6 wherein the step of associating the optical identification code on each of the integrated circuits with the respective electronically readable identification code includes the steps of:

- reading the electronically readable identification code stored in each of the integrated circuits;
- reading the optical identification code marked on each of the integrated circuits; and
- correlating the read electronically readable identification code with the read optical identification code for each of the integrated circuits.

8. The method of claim 6 wherein the step of associating the optical identification code on each of the integrated circuits with the respective electronically readable identification code includes the step of encoding identical data in the optical and electronically readable identification codes.

9. The method of claim 6 wherein the step of marking each of the integrated circuits includes the step of marking respective portions of the substrate on which the integrated circuits are formed.

10. A wafer comprising a plurality of dies, each die including an integrated circuit having a programmable identification circuit that stores identification data, and each die having an optical identification mark positioned thereon and encoding information corresponding to the identification data, optical identification mark on each die being accessed through a lookup table to correspond to the electronic identification information.

11. The wafer of claim 10 wherein the programmable identification circuit includes a plurality of programmable links.

12. The wafer of claim 10 wherein the optical identification mark encodes information identical to the identification data.

13. The wafer of claim 10 wherein the identification data uniquely distinguishes each of the dies.

14. A plurality of integrated circuit chips, each comprising:

- a housing;
- an integrated circuit enclosed within the housing and including an identification circuit that stores identification data distinguishing each of the integrated circuit chips from one another; and
- an optical mark positioned on an exterior surface of the housing and encoding identification information being

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accessed through a lookup table to correspond to the identification data.

15. The integrated circuit chips of claim 14, further comprising electrical contacts connected to said housing and adapted to provide electrical connection between the integrated circuit and circuitry external to the housing.

16. The integrated circuit chips of claim 14 wherein the optical mark is a first optical mark encoding first identification information, and further comprising a second optical mark positioned on the integrated circuit enclosed within the housing and encoding second identification information corresponding to the identification data.

17. The integrated circuit chips of claim 16 wherein the first identification information is identical to the second identification information.

18. The integrated circuit chips of claim 14 wherein the identification information is the same as the identification data.

19. A method of identifying a plurality of substantially identical integrated circuits formed on a common substrate, each of the integrated circuits being formed on a respective one of a plurality of substrate dies, the method comprising:

programming each of the plurality of integrated circuits with respective electronic identification information for each of the integrated circuits; and

marking each of the dies with optical identification code which corresponds with the respective electronic identification information;

reading the optical identification code on each of the integrated circuits;

reading the electronic identification information from each of the integrated circuits; and

accessing a lookup table to associate the optical identification code on each of the integrated circuits with the corresponding electronic identification information.

20. The method of claim 19 wherein the electronic identification information is distinct for each of the integrated circuits.

21. The method of claim 19 wherein the optical identification code is distinct for each of the dies.

22. The method of claim 19 wherein the optical identification code and the electronic identification information include identical data.

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